

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Koji NOZAKI et al.**

Group Art Unit: **1795**

Application Number: **10/623,679**

Examiner: **Amanda C. Walke**

Filed: **July 22, 2003**

Confirmation Number: **5083**

For: **RESIST PATTERN THICKENING MATERIAL, RESIST
PATTERN AND PROCESS FOR FORMING THE SAME, AND
SEMICONDUCTOR DEVICE AND PROCESS FOR
MANUFACTURING THE SAME**

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Attorney Docket Number: **030891**
Customer Number: **38834**

AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCESSING REQUESTED

DO NOT ENTER: /ACW/

11/03/2008

MAILSTOP: AF

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

October 30, 2008

Sir:

This paper is filed in response to the Office Action dated May 30, 2008, the response due date extended to October 30, 2008 by a two-months Extension of Time.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 12 of this paper.